leeno.com

Global Leading Company with World’s Best Technology

LEENO

DISCLAIMER

All Information about our company's financial outcome in this material were written by Korean International Financial Reporting Standards.

In addition, This material includes information about the future predictions which can be affected by known or unknown risks and uncertainties.

The Future business prospect is supposed to be check. Because, Many such factors such as market situation and business strategy will be important in determining our future results.
Up-to-date our company information is notified in our website. (https://leeno.com)

Feel free to contact us with any further questions

Leeno Industrial Inc
Yongki Choi /CFO +82-51-831-3232
JinCheol Kim/ IR Manager +82-51-831-4931 jckim@leeno.co.kr

LEENO LEENO IND. INC.

Contents

About ‘LEENO’

LEENO

Company Name	Leeno Industrial Inc.	
CEO	Chae-Yoon, Lee	
Foundation	NOV 1978 (Incorporated in DEC 1996)	
Business Category	Manufacture Semiconductor Test Probe and Socket	
Capital Stock	(KRW) 7.62 Billion won (`24)	(KRW) 7.62 Billion won (`25.3Q)
Revenue	(KRW) 278.2 Billion won (`24)	(KRW) 287.8 Billion won (`25.3Q)
Number of Employees	636 persons (`24)	666 persons (`25.3Q)
Head Office Location	10, MIEUMSANDAN-RO 105BEON-GIL, GANGSEO-GU, BUSAN, KOREA	
Homepage	https://leeno.com	

MAIN HISTORY

2001.	12.	Listed on KOSDAQ(058470)
2003.	10.	Appointed "Prospective Exporter, Small&Medium Business"
2004.	12.	Certified by DAS for ISO 9001
	11.	Received an award from Korean prime minister for excellence in regional innovation
2005.	9.	Appointed "Excellent Business" and awarded Korea Productivity Award
	11.	Awarded “10 Million Dollar Export Achievement Award”
2006.	11.	Certified by DAS for ISO 14001
2007.	1.	Appointed "Technology Innovative Small and Medium Enterprise"
	7.	Awarded “Grand Prize of Small and Medium Business people In Busan”
2010.	1.	Concluding a contract to supply the probe for supersonic to Siemens
	11.	Awarded “20 Million Dollar Export Achievement Award”
2012.	1.	Certified ISO13485
2013.	5.	Voted World Class 300
	6.	Bonus Issue
	8.	Moved in to New extend Head office
	12.	Awarded “30 Million Dollar Export Achievement Award”
2014.	3.	Awarded “Tin Tower Order of Industrial Service Merit”
2016.	3.	Awarded Citation in ‘Taxpayer day’
	12.	Awarded “50 Million Dollar Export Achievement Award”
2017.	12.	Awarded “70 Million Dollar Export Achievement Award”
2020.	2.	Completed “NOKSAN Factory” for Medical and Plating part.
2021.	12.	Awarded “100 Million Dollar Export Achievement Award”
2022.	12.	Awarded “200 Million Dollar Export Achievement Award”
2023.	12.	Certified ISO45001
2024.	11.	Selected “Time-honored Business”

Competitiveness

World Class Manufacturing

All manufacturing done in-house

- 01 Design
- 02 Analysis
- 03 Durability
- 04 Inspection
- 05 Assembly
- 06 Heat treatment & Plating
- 07 Spring
- 08 Molding
- 09 MCT
- 10 FAB

Consistent, Quality Products

GERMAN CERT
Quality Management System Certificate

LEENO INDUSTRIAL INC.

#10 Mieumsandan-ro 105beon-gil, Gangseo-gu, Busan, Korea

German Cert Co., Ltd. Hereby certifies that the Quality Management System of the above organization has been evaluated and found to be in line with the requirements of the following standard:

ISO 9001:2015

For the scope of

Design, Development, Manufacture and Service of Spring Contact Probe(Leeno Pin) and IC Test Socket

Certificate Number : GQ-210370

Initial Certification Date : 28 December 2004
Certification Date : 13 September 2022
Expiry Date : 12 September 2025
Issue Date : 08 September 2022

Baek Woo Ki
Scheme Manager

GERMAN CERT
QUALITY MANAGEMENT SYSTEM

GERMAN CERT
Environmental Management System Certificate

LEENO INDUSTRIAL INC.

#10 Mieumsandan-ro 105beon-gil, Gangseo-gu, Busan, Korea

German Cert Co., Ltd. Hereby certifies that the Environmental Management System of the above organization has been evaluated and found to be in line with the requirements of the following standard:

ISO 14001:2015

For the scope of

Design, Development and Manufacture of Spring Contact Probe(Leeno Pin) and IC Test Socket
IAF Code: 19

Certificate Number : GE-210161

Initial Certification Date : 26 September 2008
Certification Date : 19 September 2023
Expiry Date : 18 September 2026
Issue Date : 08 September 2023

Baek Woo Ki
Scheme Manager

GERMAN CERT
ENVIRONMENTAL MANAGEMENT SYSTEM

SZUTEST

CERTIFICATE
Medical Devices Quality Management System
CERTIFICATE NO: 3401201901

LEENO INDUSTRIAL INC.
Head Office : 10, Mieumsandan-ro 105beon-gil, Gangseo-gu, Busan, Republic of KOREA
Factory : 24, Noksansandan 261-ro 23beon-gil, Gangseo-gu, Busan, Republic of KOREA

EN ISO 13485:2016

Development, Production & Sales of Ultrasonic Probe's Component

Approves that the Medical Devices Quality Management System implemented for above scope.

First Issue Date 19.01.2012
Issue Date 14.01.2021
Expiry Date 13.01.2024
Revision Date/No 14.01.2021 / 4

Szutest.com.tr

bsi.

Certificate of Registration

OCCUPATIONAL HEALTH & SAFETY MANAGEMENT SYSTEM - ISO 45001:2018

This is to certify that: LEENO INDUSTRIAL INC.
10
Mieumsandan-ro 105beon-gil,
Gangseo-gu,
Busan
46748
Republic of Korea

Holds Certificate No: OHS 800791

and operates an Occupational Health and Safety Management System which complies with the requirements of ISO 45001:2018 for the following scope:

The design and manufacture of spring contact probe(Leeno Pin), IC test socket and ultrasonic probe's components.

For and on behalf of BSI: Michael Lam, Managing Director Assurance - APAC

Original Registration Date: 2023-12-20
Latest Revision Date: 2023-12-20
Effective Date: 2023-12-20
Expiry Date: 2026-12-19

Page: 1 of 2

...making excellence a habit.™

Major Clients

LEENO

Domestic Company
791 (Clients)

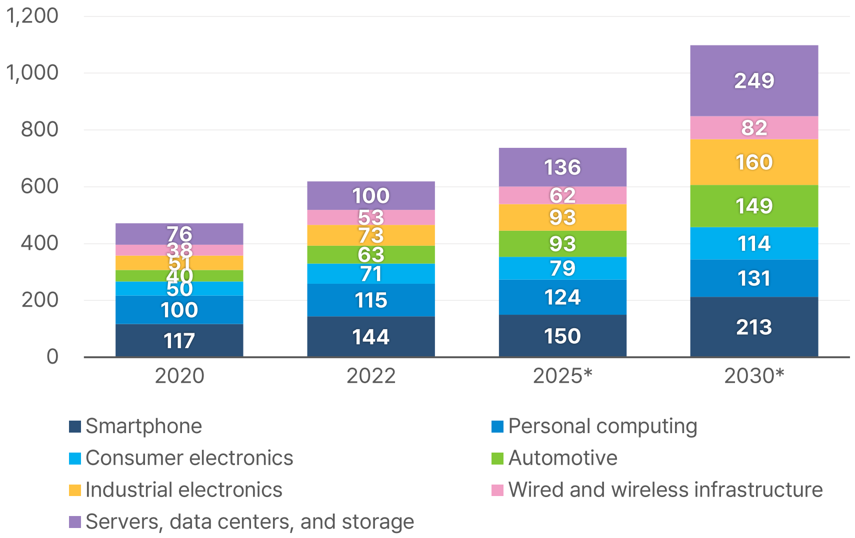
Oversea Company
150 (Clients)

※ Based on sales of 2024

Semiconductor market size worldwide from 2020 to 2030, by application

(units : billion U.S. dollars)

Source : Statista(Feb, 2023)

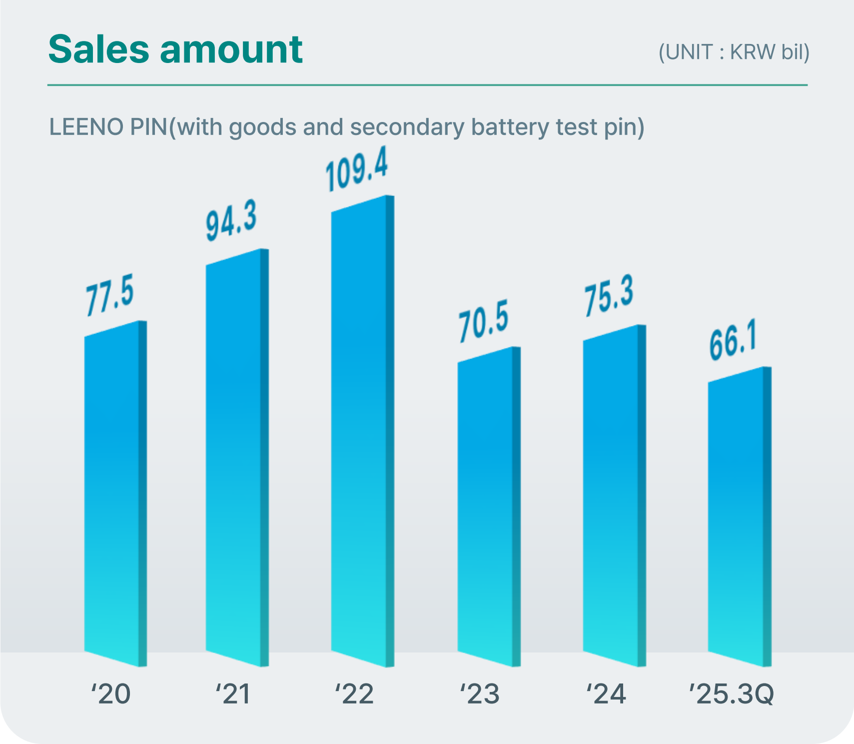


Semiconductor market size worldwide by application will total 1,098 billion dollars in 2030, according to Statista. In addition, smartphone(213 billion dollars), Servers & data centers & storage(249 billion dollars), Personal computing(131 billion dollars), Automotive(149 billion dollars), Industrial electronics(160 billion dollars), Consumer electronics(114 billion dollars) and Wired & wireless infrastructure(82 billion dollars) is expected to growth in 2030.

According to Current Trend and The Fourth Industrial Revolution(such as Iot, AI, 5G, VR, AR, Big-data, Metaverse, Automatic Driving & Electronic Car), As types and functions of non-memory and memory semiconductors go into The Devices is diversifying, Demands for functions and characteristics in Semiconductor testing market is increasing. LEENO will be accompanied by the growth of the new IT market, to actively participate in the needs of the semiconductor test market with LEENO PIN and IC TEST SOCKET.

LEENO PIN

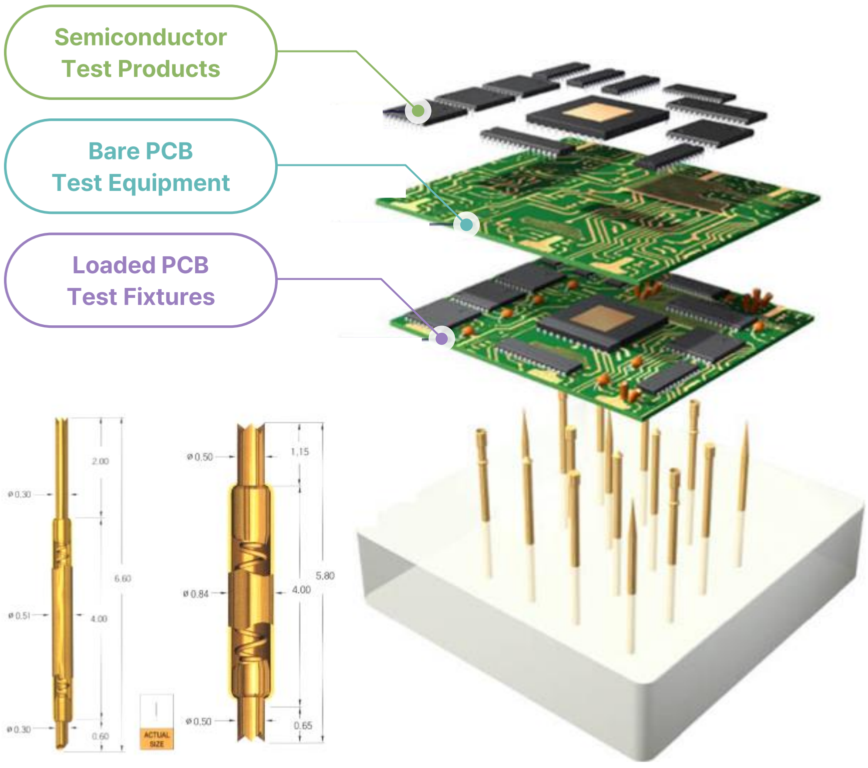
- ☑ Contact with **electronic equipment** and **PCB circuit** to check whether properly to make or not
- ☑ LEENO PIN is our own-brand as test probe pin, and about **940 companies**(Based on sales of 2024) **are using** 'LEENO PIN'
- ☑ Recently, Along with high demand of Fine Pitch Probe with variety of electronic equipment, we are satisfied our customer's needs providing **high quality and competitive pricing.**



Sales amount

(UNIT : KRW bil)

LEENO PIN(with goods and secondary battery test pin)



Semiconductor Test Products

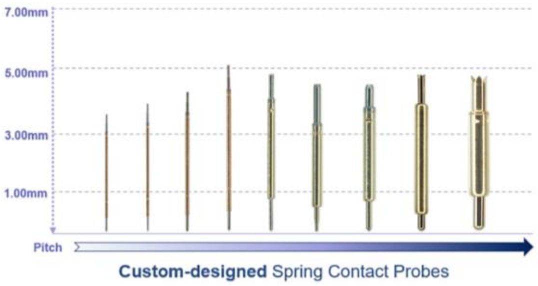
Bare PCB Test Equipment

Loaded PCB Test Fixtures

LEENO PIN

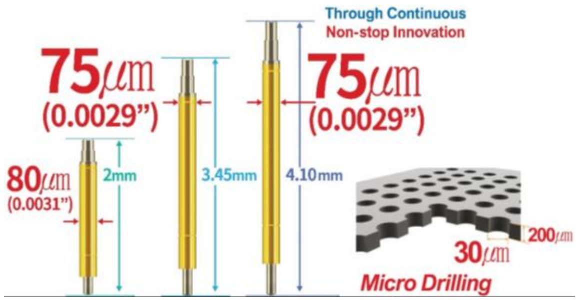
Spring Contact Probe

LEENO possesses the capability to offer custom-designed spring contact probes, manufactured 100% in-house process with the shortest lead time possible.



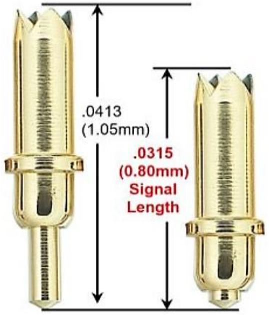
Fine Pitch Probe

Thinnest & Shortest Fine Pitch Spring Contact Probes specifically designed for Wafer Level (RF) testing purpose.



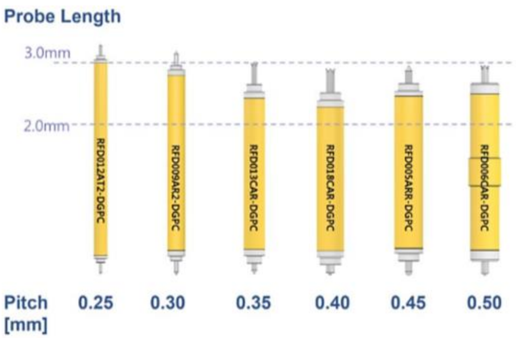
0.80mm Probe

Shortest Spring Contact Probe specifically designed for High Speed testing purpose.



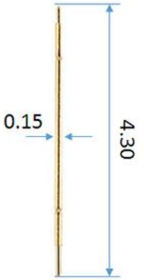
Coaxial Probe

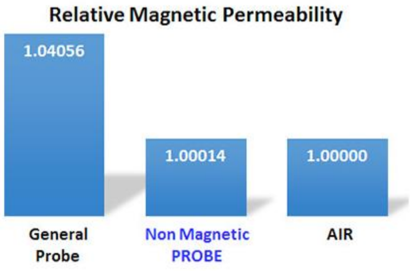
LEENO has successfully developed Coaxial Structured Spring Contact Probes that can be applied to Non-coaxial socket housings.



Non Magnetic Probe

Leeno has successfully developed fine-pitch non-magnetic springs used in proximity switches, position/current sensing, and speed detection in various fields such as mobile, automotive, and industrial applications. Using its precision technology, LEENO offers customized non-magnetic probes that can be used for testing navigation devices.





ICT Probe

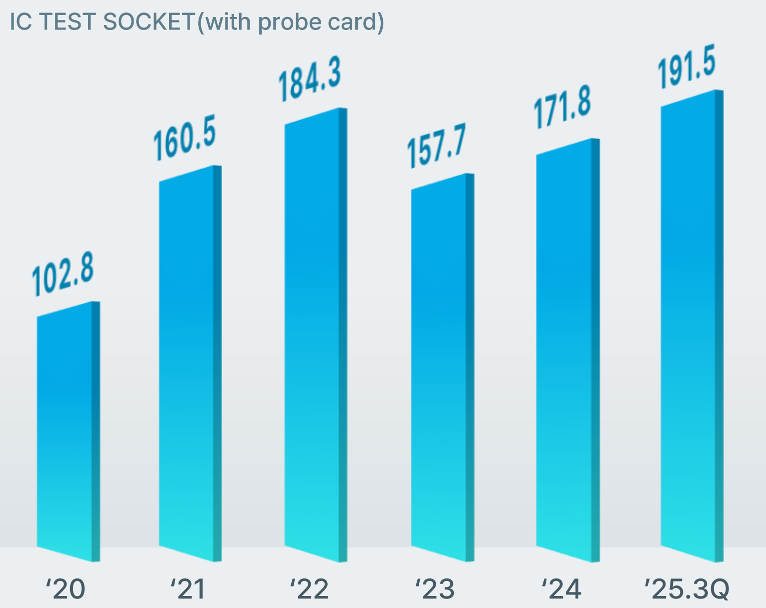
LEENO provides a wide variety of choices for ICT probes, offering over 1,000 standard models, as well as custom-designed ICT probes specially made to the customer's specifications

IC TEST SOCKET

- ☑ IC Test socket **has been used to test memory and non-memory IC semiconductor**. The purpose of this is to test electrical signal after contacting package which is located in test socket.
- ☑ Our **innovative vertical type in IC test socket** has been commercialized for 20 years through out developing innovative technology

Sales amount

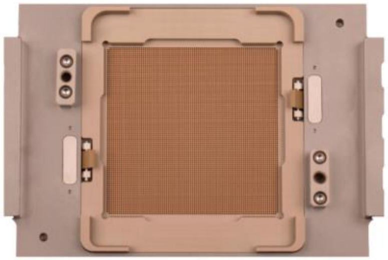
(UNIT : KRW bil)


IC TEST SOCKET(with probe card)

IC TEST SOCKET

System Level Test Socket

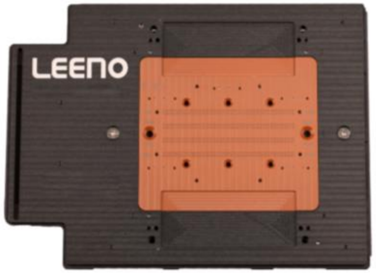
Proven capability in providing large volume custom-designed System Level Test Sockets for various device types & applications to meet the increasing demand for System Level Testing.



RF Device Test Socket

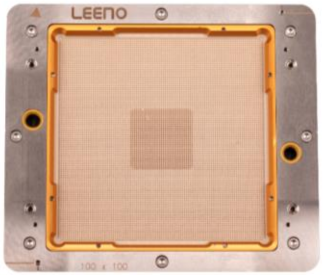
(Coaxial Socket)

With unparalleled technology, coaxial structure, and high-precision machining equipment, LEENO can provide RF test socket with high bandwidth, impedance matching and high frequency up to 100Ghz.



Large Device Test Socket

Proven Capability in providing general/coaxial testing solutions for large-size devices through FEM Simulation(structural deformation/Stress) & RF Simulation(112Gbps/224Gbps).

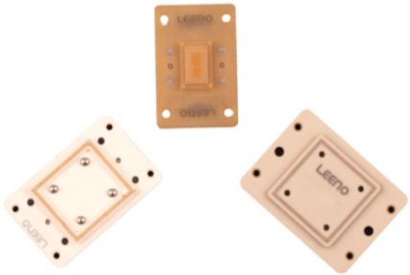


High Power Cooling Lid

LEENO can provide effective cooling lid solutions based on thermal simulations to validate heat dissipation efficiency. LEENO has accumulated knowledge on thermodynamics and vast experience in actual testing.

Memory Device Test Socket

With advanced precision injection molding equipment & patented technologies, LEENO can provide various test sockets for all kinds of memory devices.

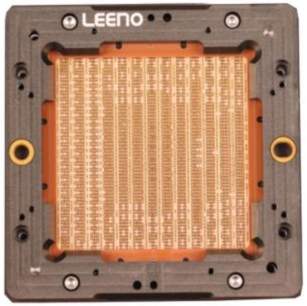


Elastomer Socket

LEENO possesses its own design capabilities and manufacturing facilities, allowing us to create a unique structure of conductive particles embedded in silicone rubber.

Strip Test Socket

LEENO can design and manufacture Multi-site Strip Test Socket which can accommodate various device types & testing requirements.



Kelvin Socket

To meet the increasing requirement of accurate & stable voltage measurement, We have been supplying Full Kelvin or Mixed Kelvin Socket to many global customers.

PROBE HEAD(CARD)

☑ The whole process semiconductor **inspection equipment to test electrical** characteristics in separated chips in wafer.

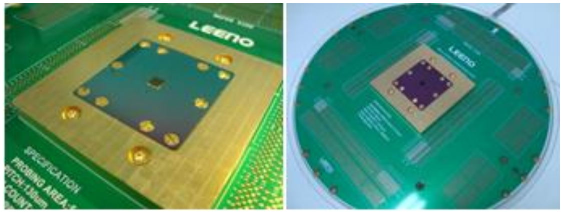
☑ LEENO is the **best leading technology company** to provide solution in competitive accelerating and evolved test market.

- 01 Long life Cycle
- 02 Quick Delivery
- 03 High Speed
- 04 Low Cost

Semiconductor whole process (FAB)

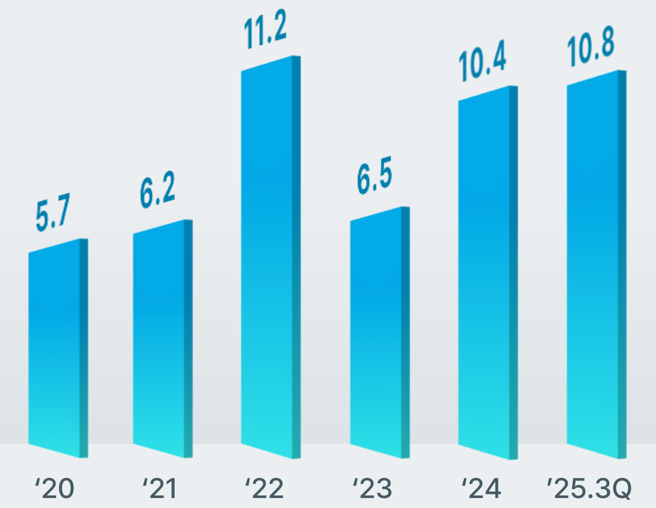
↓

Wafer level test (LEENO PROBE CARD)



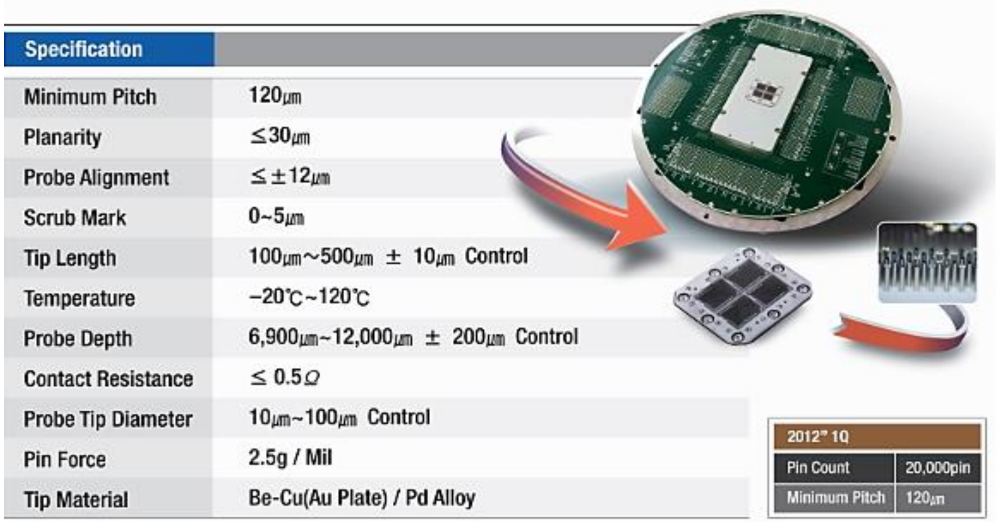
Sales amount

(UNIT : KRW bil)



Wafer Level CSP/TSV Probe Card

150μm Pitch Flip Chip Quad Site Vertical Probe Card Total 13,500Pin



Specification	
Minimum Pitch	120㎛
Planarity	≤30㎛
Probe Alignment	≤±12㎛
Scrub Mark	0~5㎛
Tip Length	100㎛~500㎛ ± 10㎛ Control
Temperature	-20℃~120℃
Probe Depth	6,900㎛~12,000㎛ ± 200㎛ Control
Contact Resistance	≤ 0.5Ω
Probe Tip Diameter	10㎛~100㎛ Control
Pin Force	2.5g / Mil
Tip Material	Be-Cu(Au Plate) / Pd Alloy

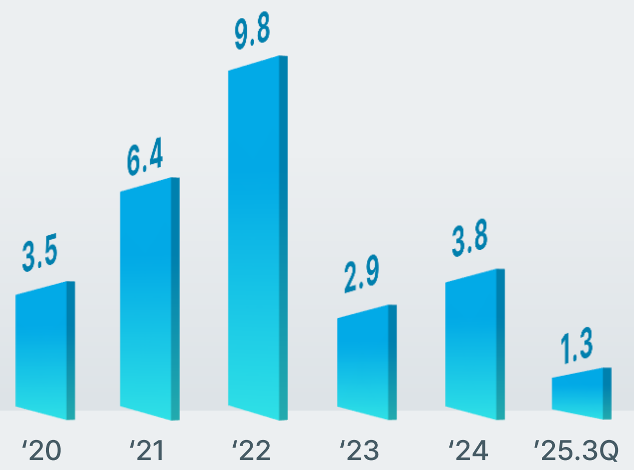
2012" 1Q	
Pin Count	20,000pin
Minimum Pitch	120㎛

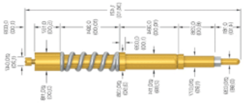
Secondary Battery Test Pin

- ☑ The demand for **secondary batteries to be used for key items in the IT sector** such as portable products is expected to increase more compared with the previous year.
- ☑ LEENO manufacture high-current test pin for hybrid car to cope with active market.
- ☑ **World-class technology and pin production experience** in domestic market make possible for the final customer to use secondary battery safely.

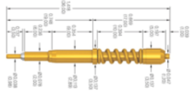
Sales amount

(UNIT : KRW bil)



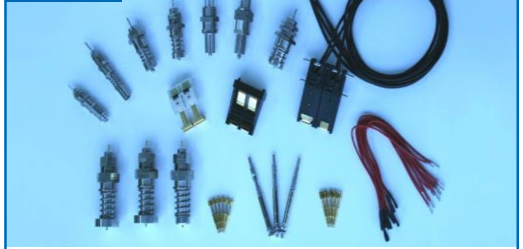


CA109

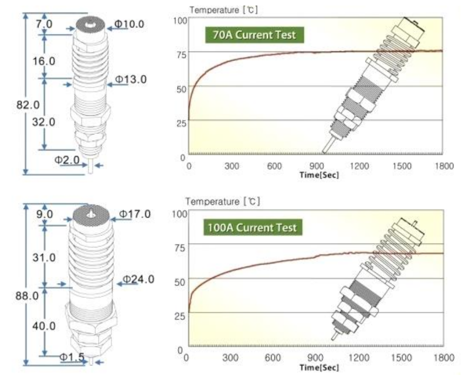


CA103

Others



Secondary battery pin and high-volume battery test pin.



Ultrasonic wave probe component

☑ 25th Jan, 2010 LEENO Industrial Inc.
makes an agreement about supplying Ultrasonic wave probe component with SIEMENS

> What is the ‘Ultrasonic wave probe’ ?
: It is single unit machine of ultrasonic diagnostic imaging device which has function to generate and detect ultrasonic wave and contacted directly with human body.

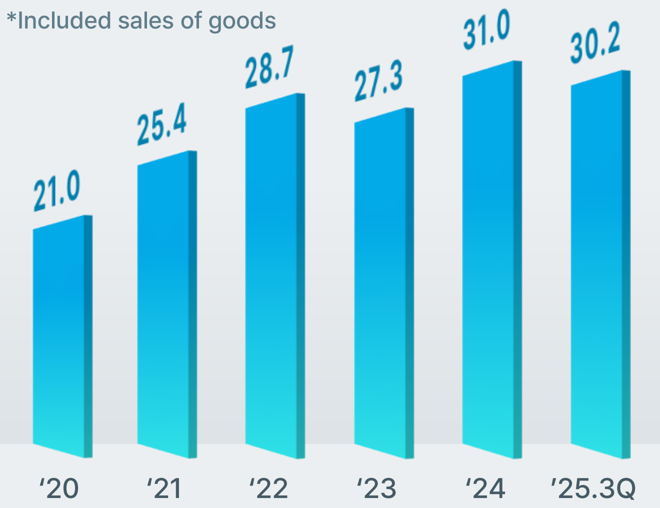
☑ This will be a base for **new growth** of LEENO’s new market
(※ Regarded as a consumable parts in ultrasonic wave diagnostic device)

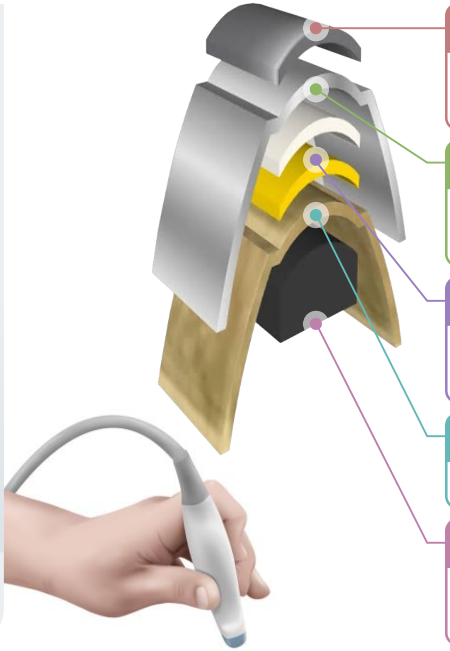
☑ Manufacture the **core part of probe**, developing high value

Sales amount

(UNIT : KRW bil)

*Included sales of goods





Lens
This part is contacted with human body directly and control ultrasonic wave’s direction.

Shield / GRS
To remove noise from ultrasonic wave prove and for electrical grounding and shielding role.

Matching Layer
To control and magnify ultrasonic wave’s direction in the ultrasonic wave probe.

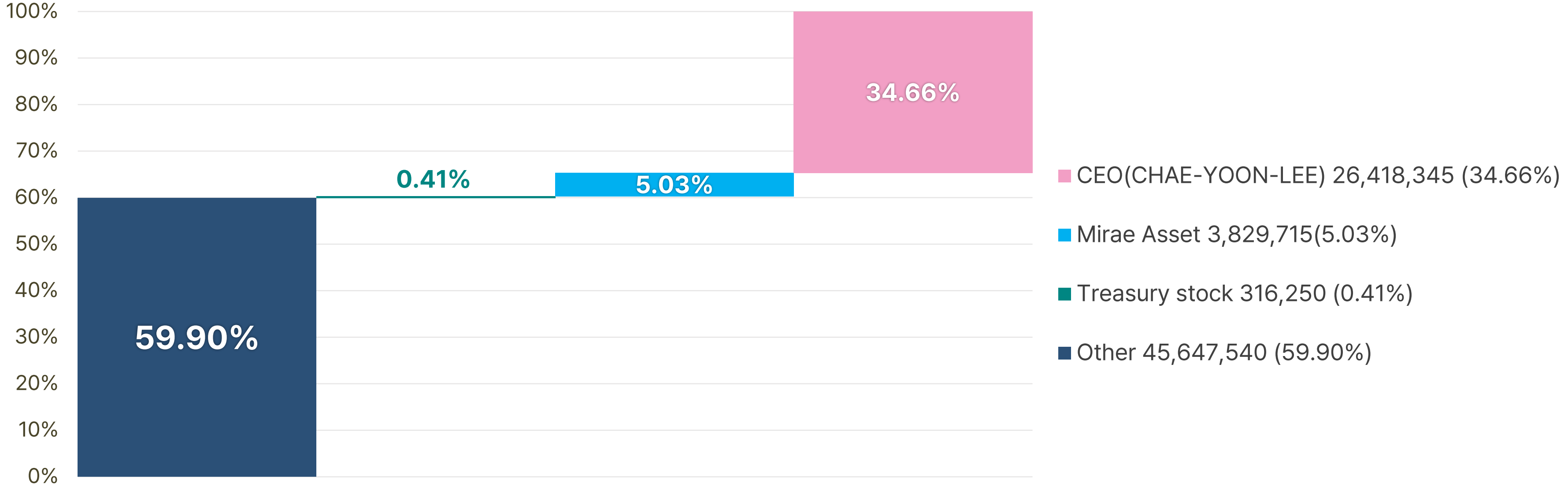
Flexible PCB
The component for applied and received voltage.

Backer
This part absorbs the backside direction’s ultrasonic wave which was generated from ultrasonic wave probe.

Stock Information

☑ LEENO is doing our **best to enhance the company's value** in return for your **trust and encouragement.**

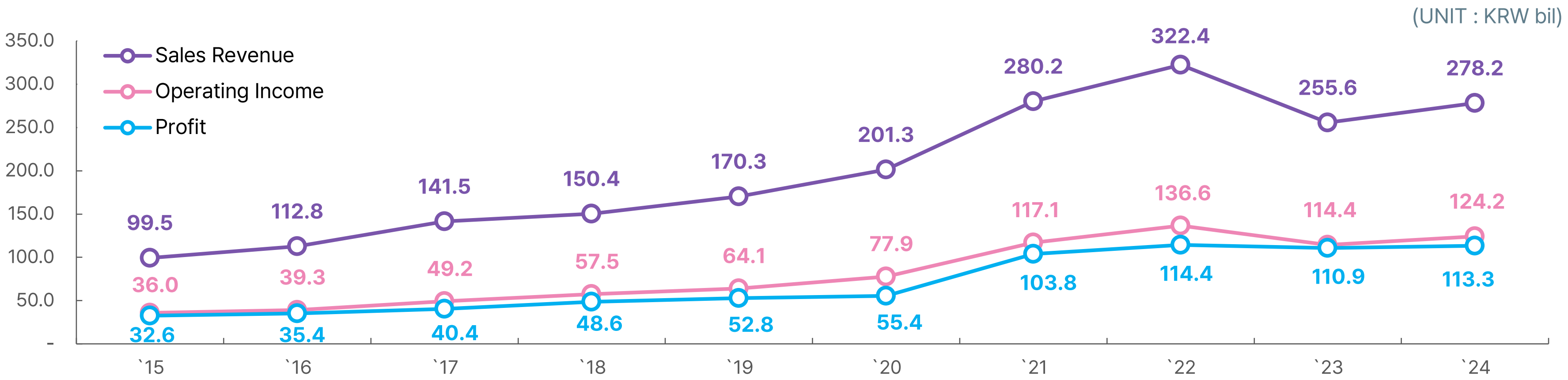
Total stocks	Treasury stocks	Capital stock
76,211,850	316,250	7,621,185,000 (KRW)



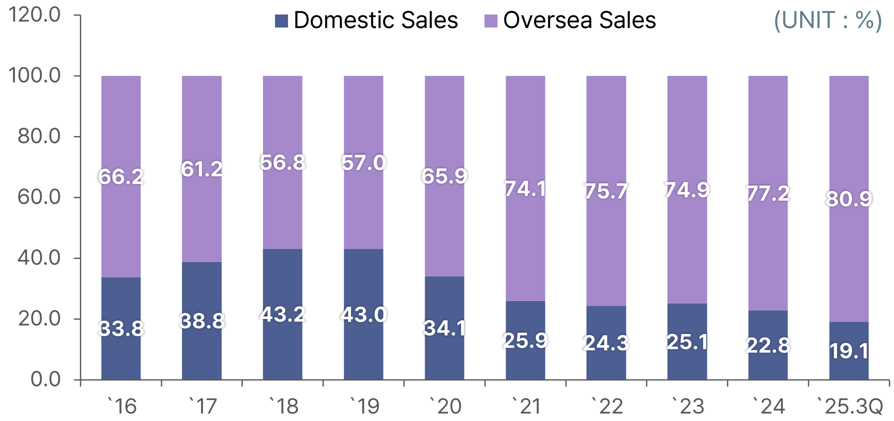
- Based on Stockholding status Report by Mirae Asset Global Investments(At November 6th, 2025)
- According to Treasury stock, Please find the Disclosure of Treasury stock at NOV 29th, 2019.
- Due to the stock split(refer to the Disclosure of stock split at FEB 11th, 2025) the total stocks has changed from 15,242,370 to 76,211,850.

Year Performance

Year Performance

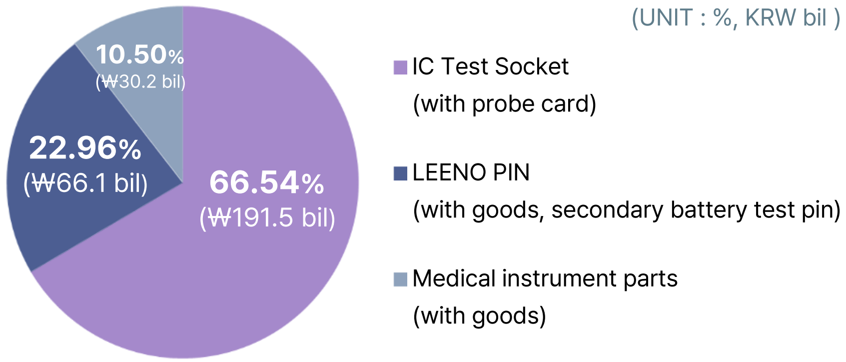


Export Ratio



Revenue Ratio

(Based on FY 2025.3Q Total Sales Revenue : 287.8 KRW bil)



Dividend

Dividend

(UNIT : KRW)

Date	Par value	Net income	Earning Per Share (EPS)	Dividend	Dividend yield ratio(%)	Total Dividend amount
`24	500	113,279,046,428	7,463	3,000	1.54	45,537,360,000
`23	500	110,923,015,440	7,308	3,000	1.48	45,537,360,000
`22	500	114,363,791,327	7,534	3,000	1.85	45,537,360,000
`21	500	103,805,815,149	6,839	2,500	1.26	37,947,800,000
`20	500	55,378,772,170	3,648	1,500	1.14	22,768,680,000

➤ About the Dividend in 2020~2024, Total Dividend amount for 15,179,220 stocks except Treasury stocks(63,250).

Stable Management

- Superior Financial structure and cashable property
- No-borrow Management & Maintenance
- Increasing of operating profit & Net income
- Maintenance of profit from high added value

Policy for Stockholders

Financial Statement

Balance Sheet

(UNIT : KRW)

	FY 2025.3Q	FY 2024
I. Current Assets	516,902,488,039	449,498,090,730
II. Non-Current Assets	245,536,181,475	207,945,690,026
Total Assets	762,438,669,514	657,443,780,756
I. Current Liabilities	67,024,547,215	30,614,692,642
II. Non-current Liabilities	5,868,616,945	4,199,975,951
Total Liabilities	72,893,164,160	34,814,668,593
I. Issued capital	7,621,185,000	7,621,185,000
II. Capital Surplus	5,601,810,444	5,601,810,444
III. Other Capital Adjustments	(2,353,516,350)	(2,353,516,350)
IV. Retained Earnings	678,676,026,260	611,759,633,069
Total Equities	689,545,505,354	622,629,112,163
Total Equities and Liabilities	762,438,669,514	657,443,780,756

Statement of comprehensive income (Accumulated)

(UNIT : KRW)

	FY 2025.3Q	FY 2024.3Q	FY 2024
I. Revenue (Sales)	287,774,135,318	194,767,344,539	278,186,189,427
II. Cost of sales	137,407,571,301	97,724,587,300	140,020,108,110
III. Gross Profit	150,366,564,017	97,042,757,239	138,166,081,317
IV. Selling General Administrative Expenses	13,723,102,572	9,861,652,077	13,964,737,445
V. Operating Income	136,643,461,445	87,181,105,162	124,201,343,872
VI. Non-operating Income	9,048,964,584	10,188,478,940	22,337,738,072
VII. Profit before tax	145,692,426,029	97,369,584,102	146,539,081,944
VIII. Income tax expense	33,323,311,544	22,390,222,205	33,260,035,516
IX. Profit	112,369,114,485	74,979,361,897	113,279,046,428
X. Other comprehensive Income	84,638,706	145,208,164	(2,186,772,331)
XI. Total comprehensive Income	112,453,753,191	75,124,570,061	111,092,274,097
XII. Basic Earnings per share	1,481	988	1,493

* The basic earnings per share for 29th fiscal year have been adjusted to reflect the stock split.

Appendix

Tester

Teradyne Advantest
Unitest Exicon...

+

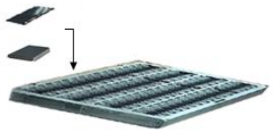
Handler

Mirae Advantest
Techwing Semes...

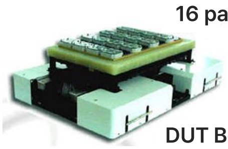
DUT(Device Under Test) Board

IC loading and unloading,
Rearrange good and bad items.

Arrangement Inside Handler



Connected to Tester



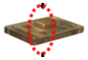
For TSOP

Contact area to Device Leads
: Sapphire

For BGA

Main part for IC Tester

What is the standard
for the exact alignment
of whole parts?



THANK YOU

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